

### Listing of Claims

1. (Previously Presented) A positive photosensitive resist composition comprising a resin binder and an encapsulated inorganic material comprising core particles having an average size less than about 10 nanometer, wherein the photoresist is sufficiently base soluble upon activation by radiation to function as a positive resist.
2. (Original) The positive photosensitive resist composition of claim 1, wherein the binder is a t-butyl blocked polyvinyl phenol.
3. (Original) The positive photosensitive resist composition of claim 1, wherein the binder is a polyvinylphenol and t-butyl acrylate copolymer.
4. (Original) The positive photosensitive resist composition of claim 1, wherein the binder is a polyvinylphenol, t-butyl acrylate and styrene terpolymer.
5. (Original) The positive photosensitive resist composition of claim 1, wherein the binder is a DNQ novalak binder.
6. (Original) The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material is silicon dioxide.
7. (Original) The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material is aluminum oxide.
8. (Original) The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material is titanium oxide.
9. (Original) The positive photosensitive resist composition of claim 1, wherein the content of the encapsulated inorganic resist material is between about 0.1% and about 90% by weight of the positive photosensitive resist composition.

10. (Original) The positive photosensitive resist composition of claim 1, wherein the content of the encapsulated inorganic material is between about 5% and about 75% by weight of the positive photosensitive resist composition.

11. (Original) The positive photosensitive resist composition of claim 1, wherein the content of the encapsulated inorganic material is between about 20% and about 50% by weight of the positive photosensitive resist composition.

12. (Original) The positive photosensitive resist composition of claim 1, wherein the binder and the encapsulated inorganic material form a clear positive photosensitive resist composition.

13. (Original) The positive photosensitive resist composition of claim 1, further comprising a surfactant.

14. (Original) The positive photosensitive resist composition of claim 1, further comprising a solvent.

15. (Canceled)

16. (Canceled)

17. (Original) The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material further comprises core particles having an average size less than about 5 nm.